

## ABSTRACT OF THE INVENTION

The present invention relates to a device that includes a low-ohmic test. The device includes a metallization copper pad such as metal-six, a metal first film such as Ni that is disposed above the metallization copper pad, and a metal second film such as Au that is disposed above the metal first film. The present invention also relates to a wire-bonding process, and to a method of pulling a first wire bond and making a second wire bond.

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